

AMENDMENTS TO THE CLAIMS

This listing of claims replaces all prior versions, and listings, of claims in the application:

Listing of Claims

1-9. (Cancelled)

10. (New) A method for producing and testing an arrangement of stacked circuit boards, said method comprising the steps of:

detachably arranging at least two circuit boards having a pair of opposing circuit board terminals and a first retainer board having at least one plated hole into which a wire button contact is inserted, wherein at least one conductor is connected to the hole for providing outside access to the wire button contact, the wire button contact providing electrical connection between the pair of opposing circuit board terminals of the two circuit boards;

testing the individual functionality of the circuit boards; and,

assembling the circuit boards and the first retainer board, and ascertaining whether the overall functionality of the arrangement is acceptable.

11. (New) The method according to claim 10, wherein upon overall acceptance of the arrangement, fixedly assembling the arrangement.

12. (New) The method according to claim 10, wherein the retainer board is a multilayer board wherein dielectric layers constitute the outer layers of a mid section of the multilayer retainer board).

13. (New) The method according to claim 10, further comprising the step, subsequent to said acceptance, of inserting a second retainer board which is substantially identical to the first retainer board.

14. (New) An arrangement of stacked circuit boards adapted for testing thereof, comprising:

at least two circuit boards having a pair of opposing substrate terminals;

a retainer board having at least one plated hole into which a wire button contact is inserted, wherein at least one conductor is connected to the plated hole for providing outside access to the wire button contact, the wire button contact providing electrical connection between the pair of opposing circuit board terminals of the circuit boards.

15. (New) The arrangement according to claim 14, wherein the retainer board is a multilayer board wherein dielectric layers constitute the outer layers of a mid section of the multilayer retainer board.

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